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Kirkland

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(54) **WAFER SUPPORT RING**

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(**) Term: **15 Years**

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(51) **LOC (13) Cl.** **12-05**

(52) **U.S. Cl.**
USPC **D34/29**

(58) **Field of Classification Search**
USPC D34/28–39; D15/199; D23/269; D8/352
CPC H01L 21/67259; H01L 21/67742; H01L 21/672818; H01L 21/67309; H02K 5/128
See application file for complete search history.

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(57) CLAIM

The ornamental design for a wafer support ring, as shown and described.

DESCRIPTION

FIG. **1** is a top perspective view of a wafer support ring.

FIG. **2** is a bottom perspective view of the wafer support ring.

FIG. **3** is a top plan view of the wafer support ring.

FIG. **4** is a bottom plan view of the wafer support ring.

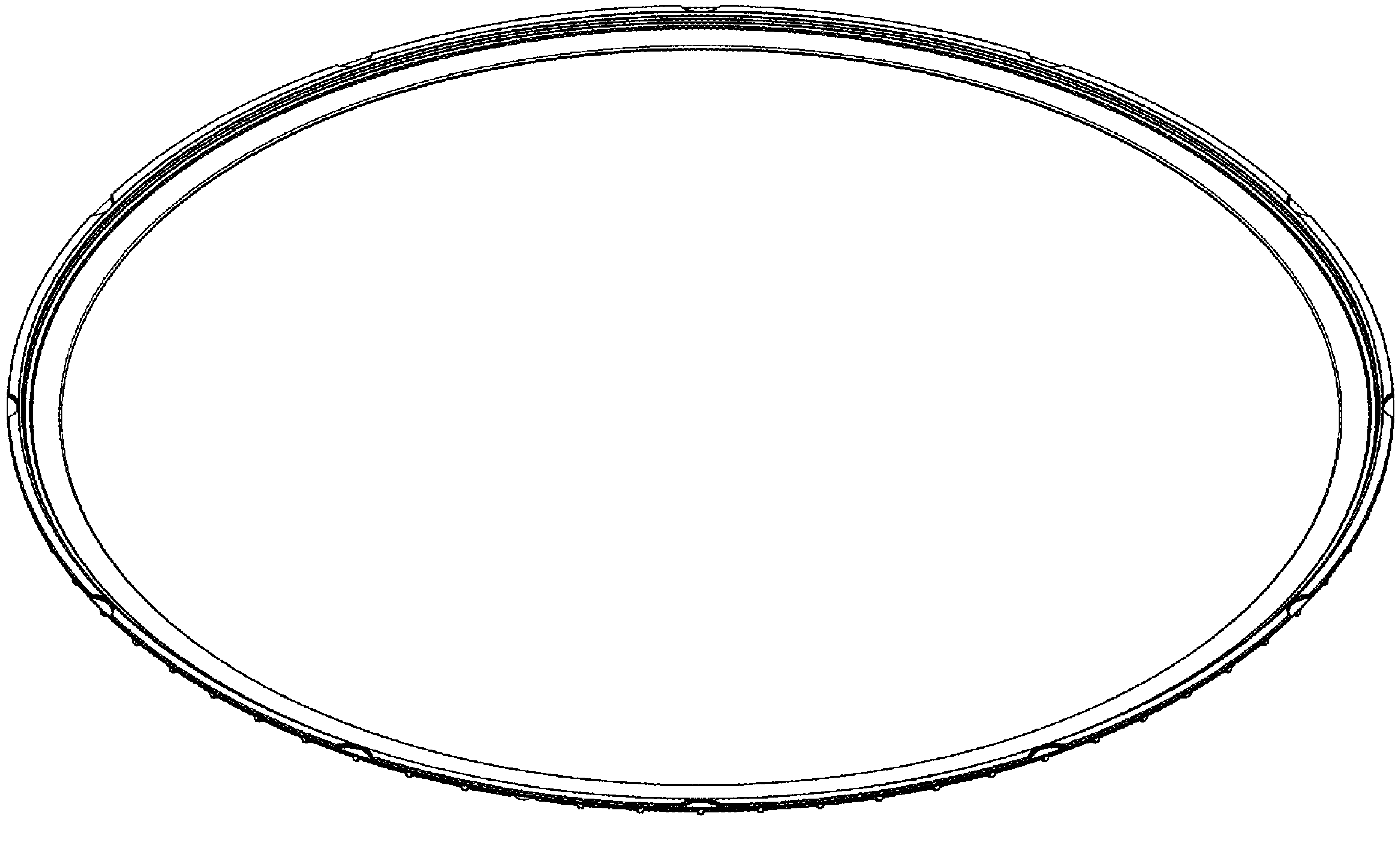
FIG. **5** is a front elevational view of the wafer support ring. The rear elevational view of the wafer support ring is a mirror image of the front elevational view.

FIG. **6** is a left side view of the wafer support ring. The right side view of the wafer support ring is a mirror image of the left side view.

FIG. **7** is an enlarged cross-sectional view of the wafer support ring taken along line **7-7** in FIG. **3**; and,

FIG. **8** is an enlarged cross-sectional view of the wafer support ring taken along line **8-8** in FIG. **3**.

1 Claim, 5 Drawing Sheets



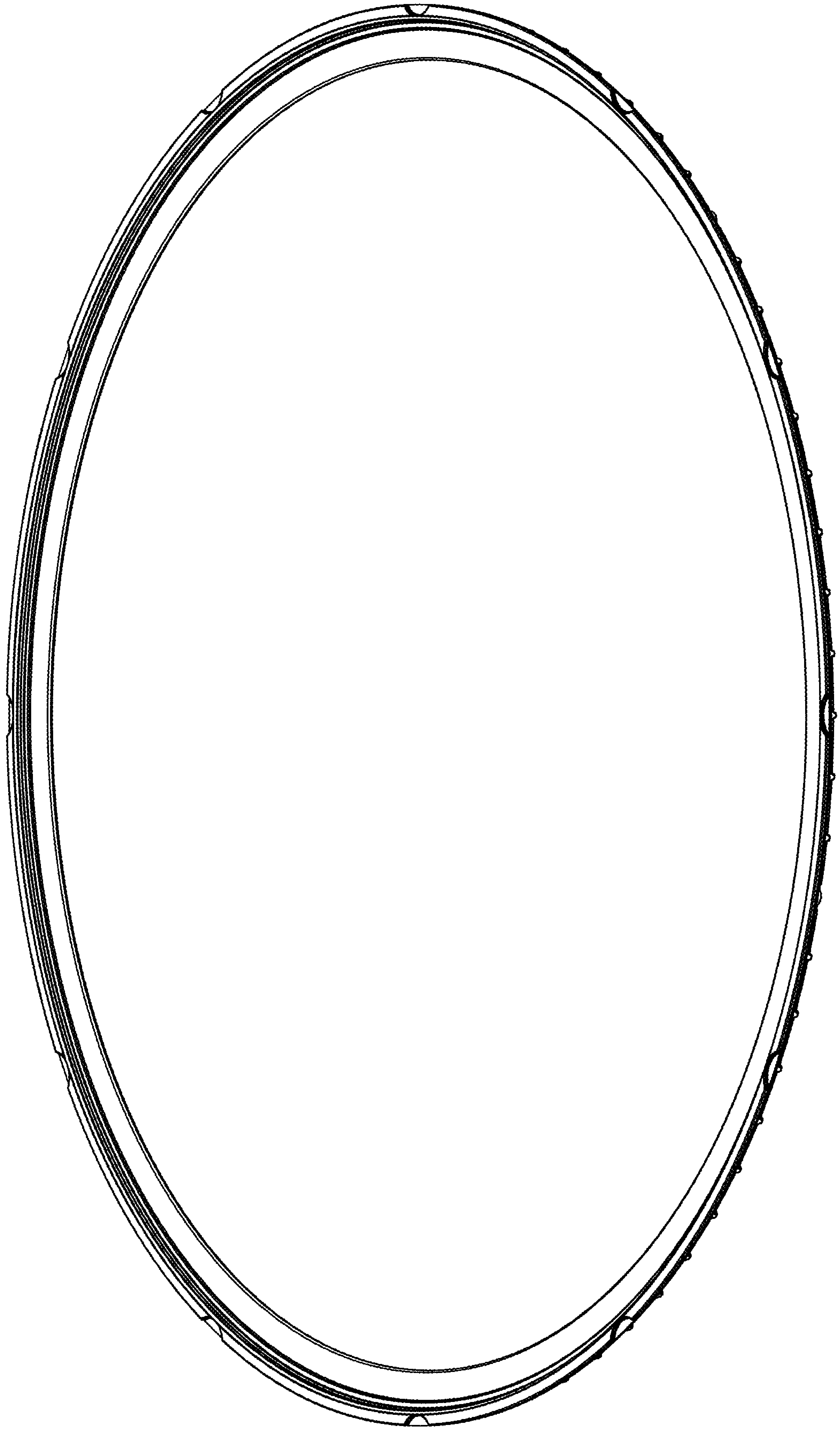


Fig. 1

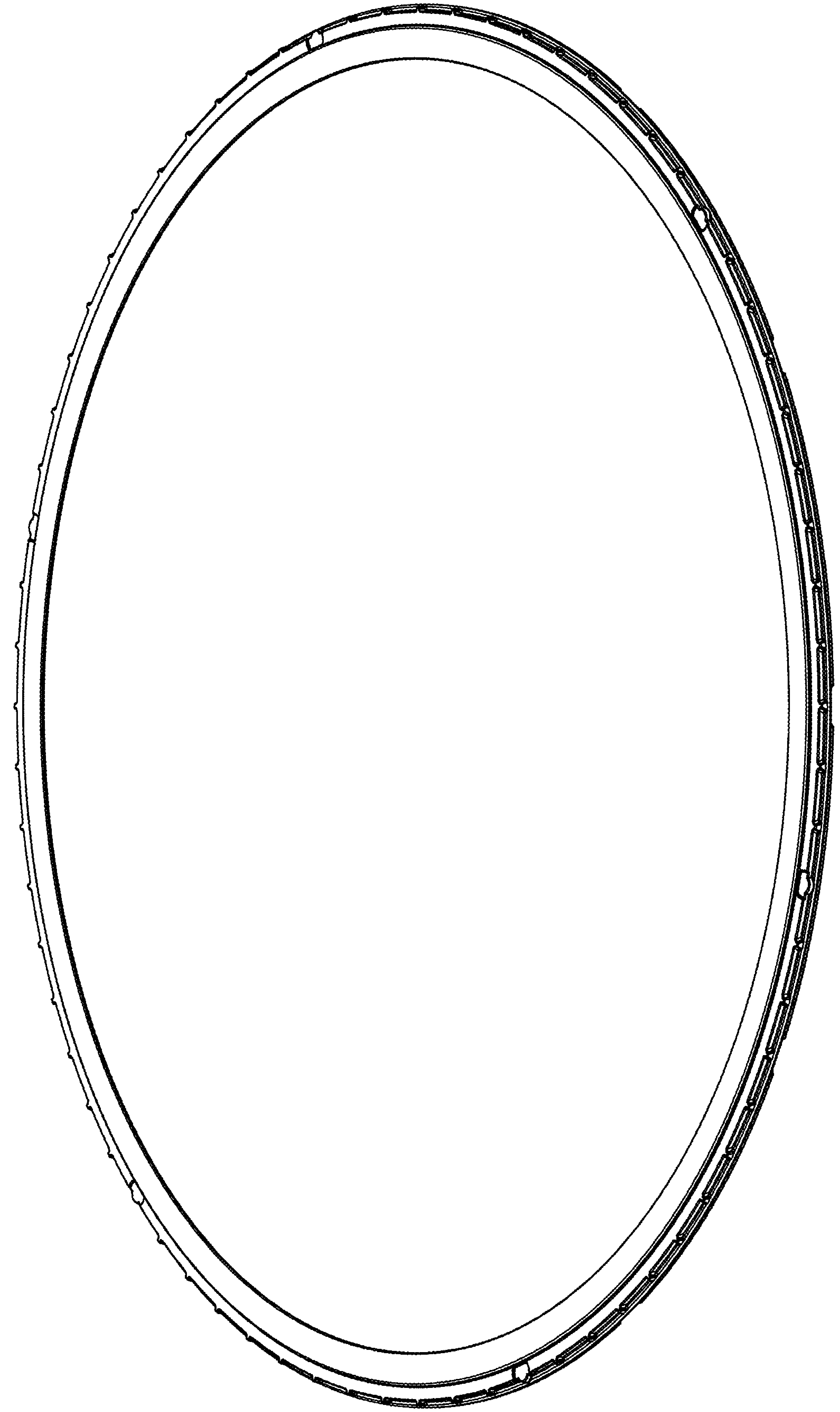


Fig. 2

Fig. 3

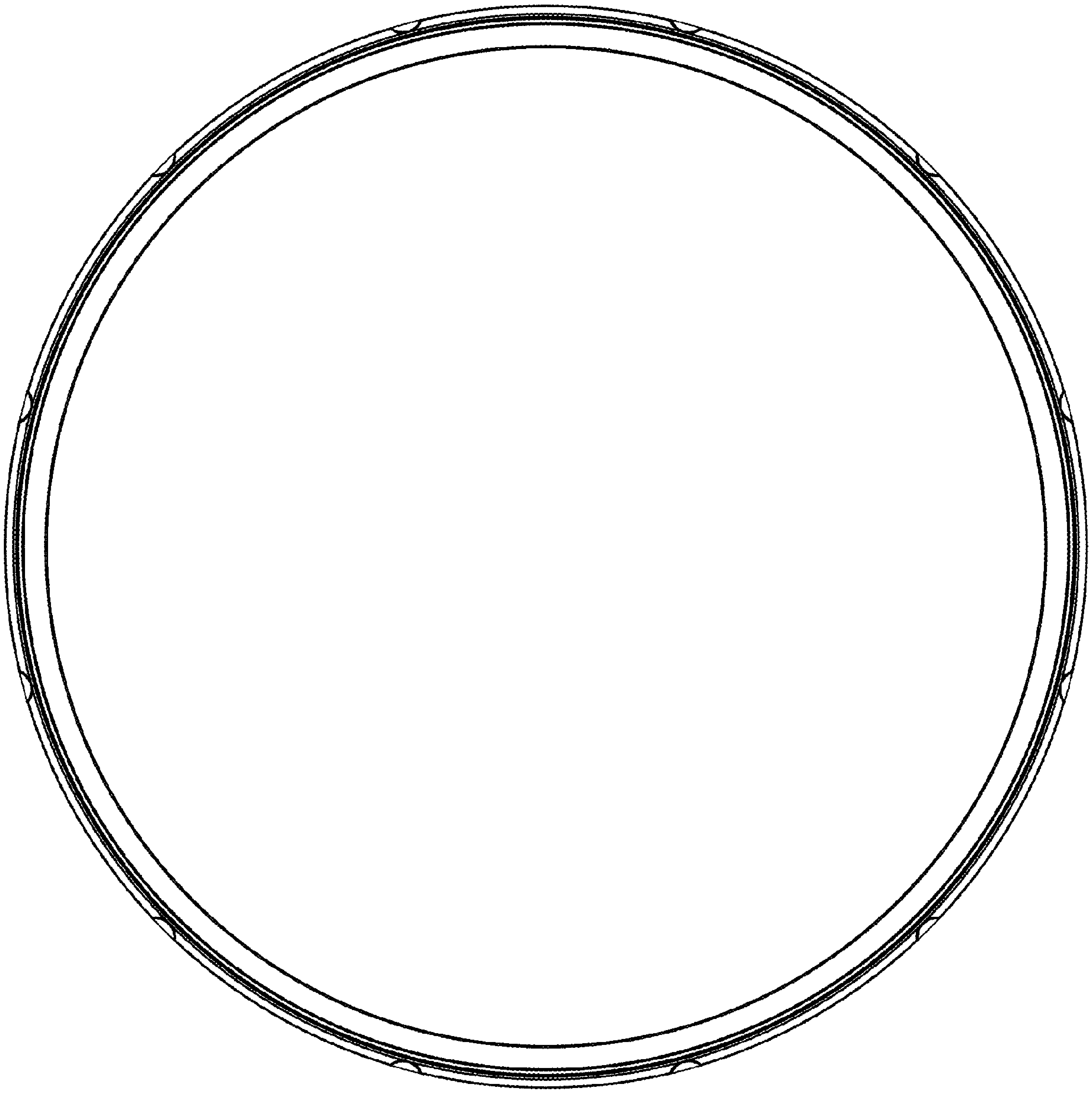


Fig. 4

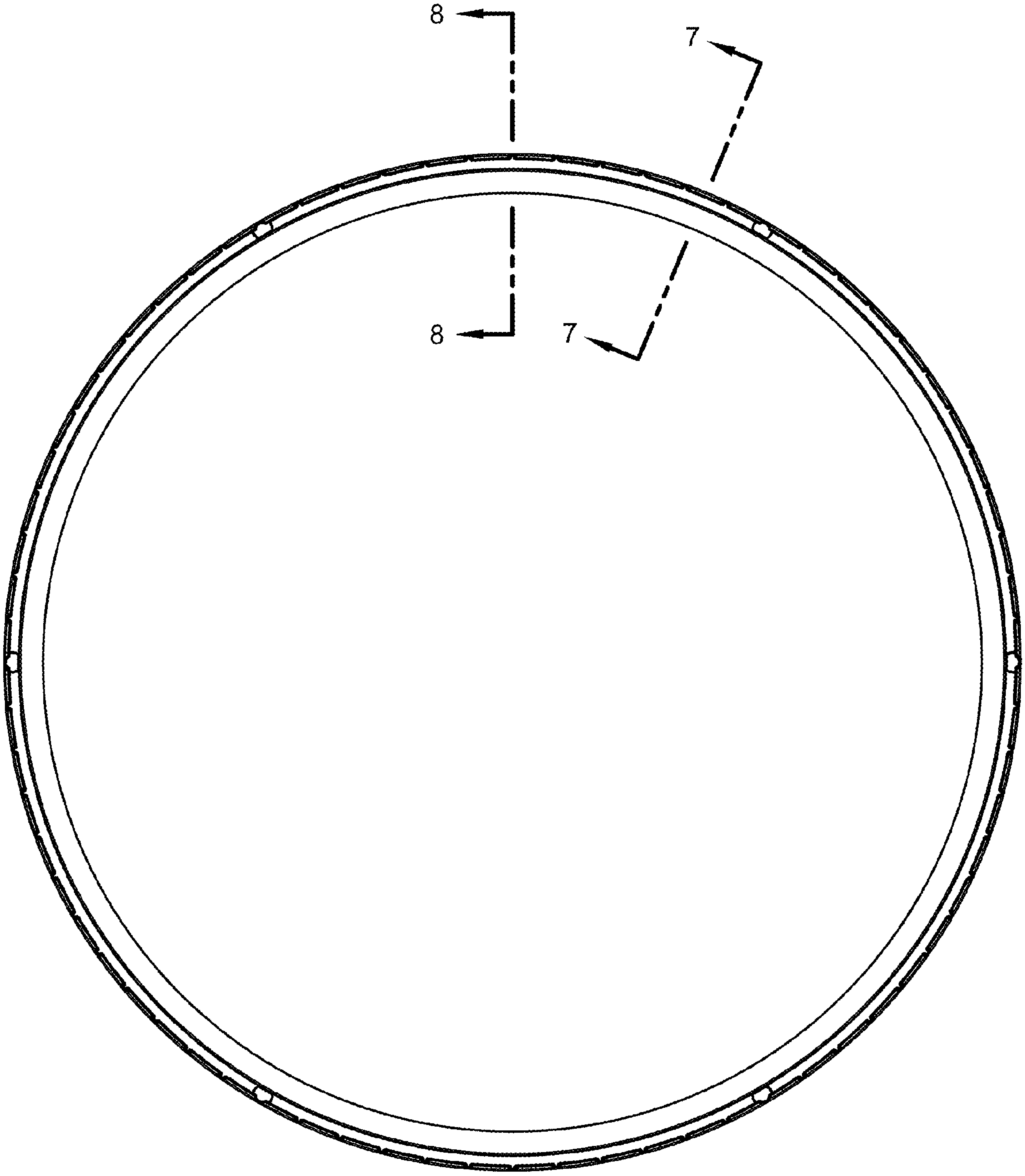


Fig. 5

Fig. 6

Fig. 7

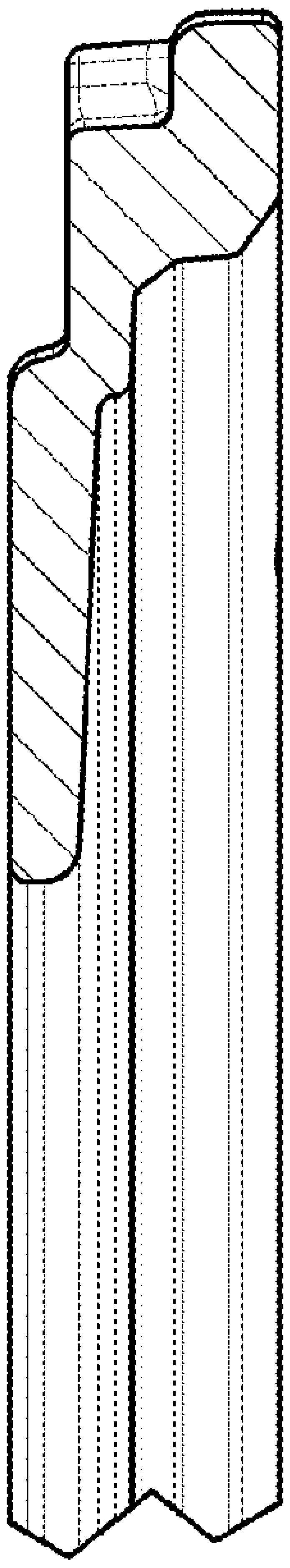


Fig. 8